



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Serial No.: 10/761,784  
Applicant: Wei Pan *et al.*  
Filed: January 21, 2004  
Group #: 2823  
Examiner: William D. Coleman

Confirmation Number: 3531

Docket No: SLA.0861  
Customer No: 27518  
For: Integrated Circuit Structure with Copper Interconnect

MS AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

**RESPONSE TO OFFICE ACTION UNDER 37 C.F.R. § 1.111  
CHANGE OF CORRESPONDENCE ADDRESS  
Introductory Comments**

In response to the Office Action dated April 15, 2005, please amend the above-identified Application as follows:

**Amendment to the Specification** None

**Amendment to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Amendment to the Drawings** None

**Remarks/Arguments** begin on page 9 of this paper.

An **Appendix** is not included.